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ENCLOSURES:

() Application _____
() Specification ____ pages
() Claims ____ pages
() Abstract ____ page(s)
() Drawing Sheets no. ____ (F) ____ (INF) ____
() Transmittal Letter
(Check \$ 86.00 No: 15019)
() Declaration/Oath
() Assignment and Cover Sheet
() Information Disclosure Statement
() Response/Amendment
() Extension of Time (In Duplicate)
() Small Entity Status
() Copy of Priority Document
 Preliminary Amendment



RE: APPLICATION ATTY/SEC: MJM/SMW

File no: 0553-0166.01

Applicant: Yamazaki et al

S.N.: 101629069 Filing Date: July 29, 2003

Wiring material AND A Semiconductor Device

Title: HAVING A WIRING USING THE MATERIAL AND

The Manufacturing Method Thereof

Due date: _____ Date Sent: 11/4/03

SEL

0553-0166.01

EDM/MJM